DuPont™ PlasmaSolv® EKC270™ post-etch residue remover

Made with DuPont™ HDA® hydroxylamine technology for enhanced performance

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Benefits
- Formulated for optimum metal stack integrity
- “Improved” wide window process capability
- Enhanced post etch residue removal
- Patented and patent pending improved reduction chemistry
- Ultra Large Scale Integration (ULSI) grade specifications for advanced wafer cleaning
- Low evaporation rate at operating temperature

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DuPont™ EKC270™ demonstrates superior performance, even under aggressive processing conditions
For more information on DuPont® PlasmaSolv® EKC270™ post-etch residue remover or other DuPont EKC Technology products, please contact your local representative, or visit our website:

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Caution: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see “DuPont Medical Caution Statement: H-81459 or H-50102-2”